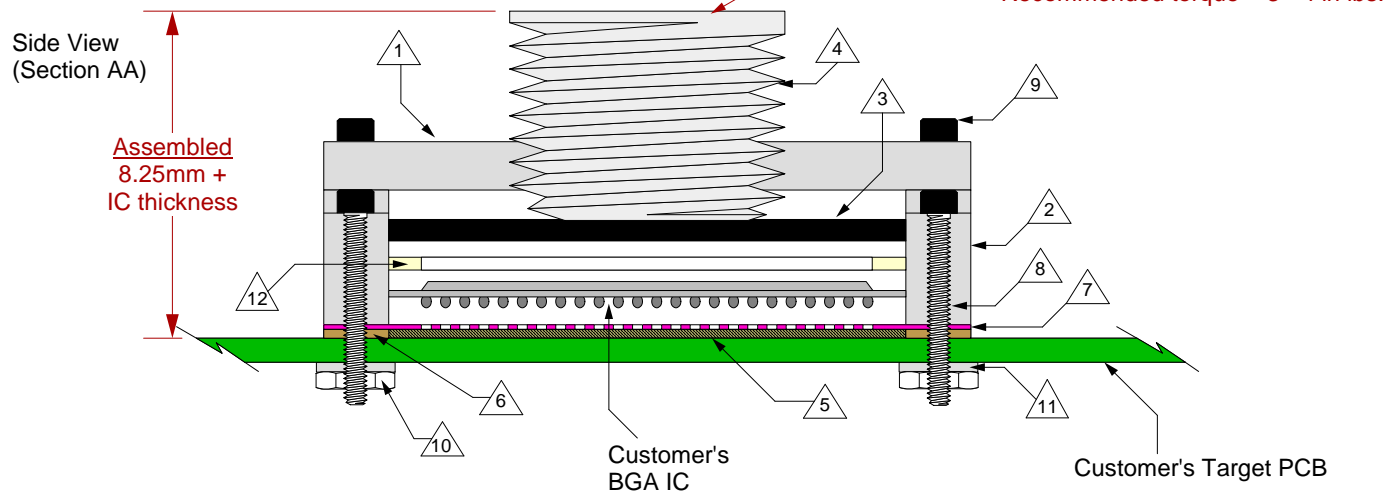
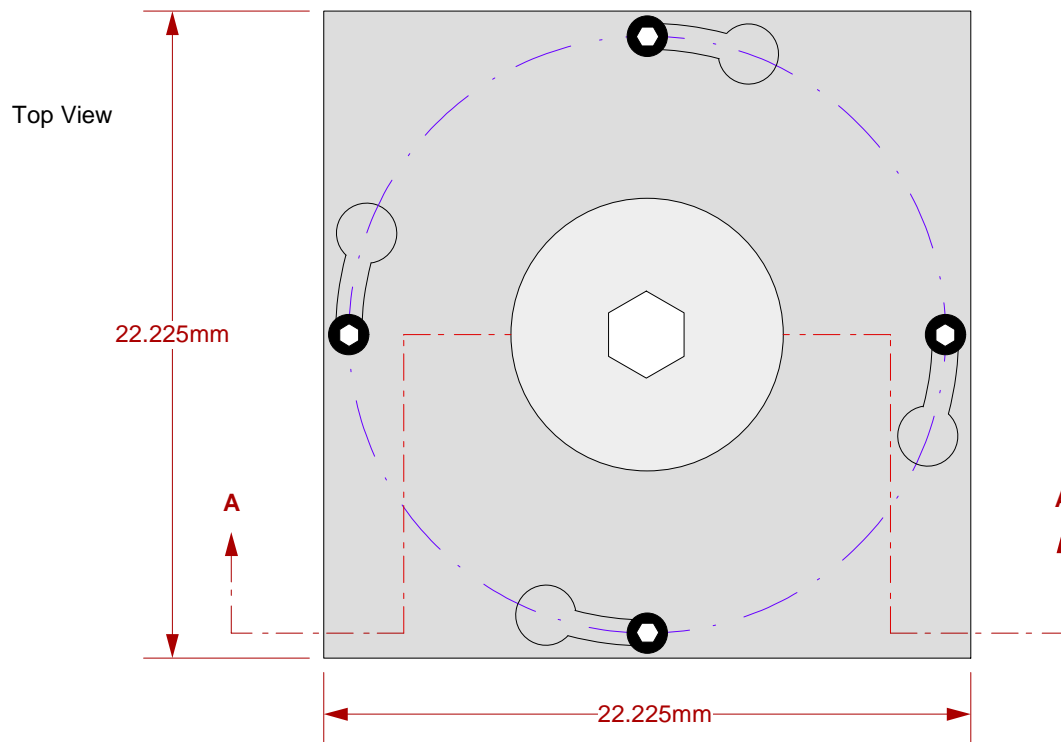


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- Socket base: Black anodized Aluminum. Thickness = 5mm.
- Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- Ball Guide: Kapton polyimide.
- Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- IC Frame: FR4

SG-BGA-6143 Drawing

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Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

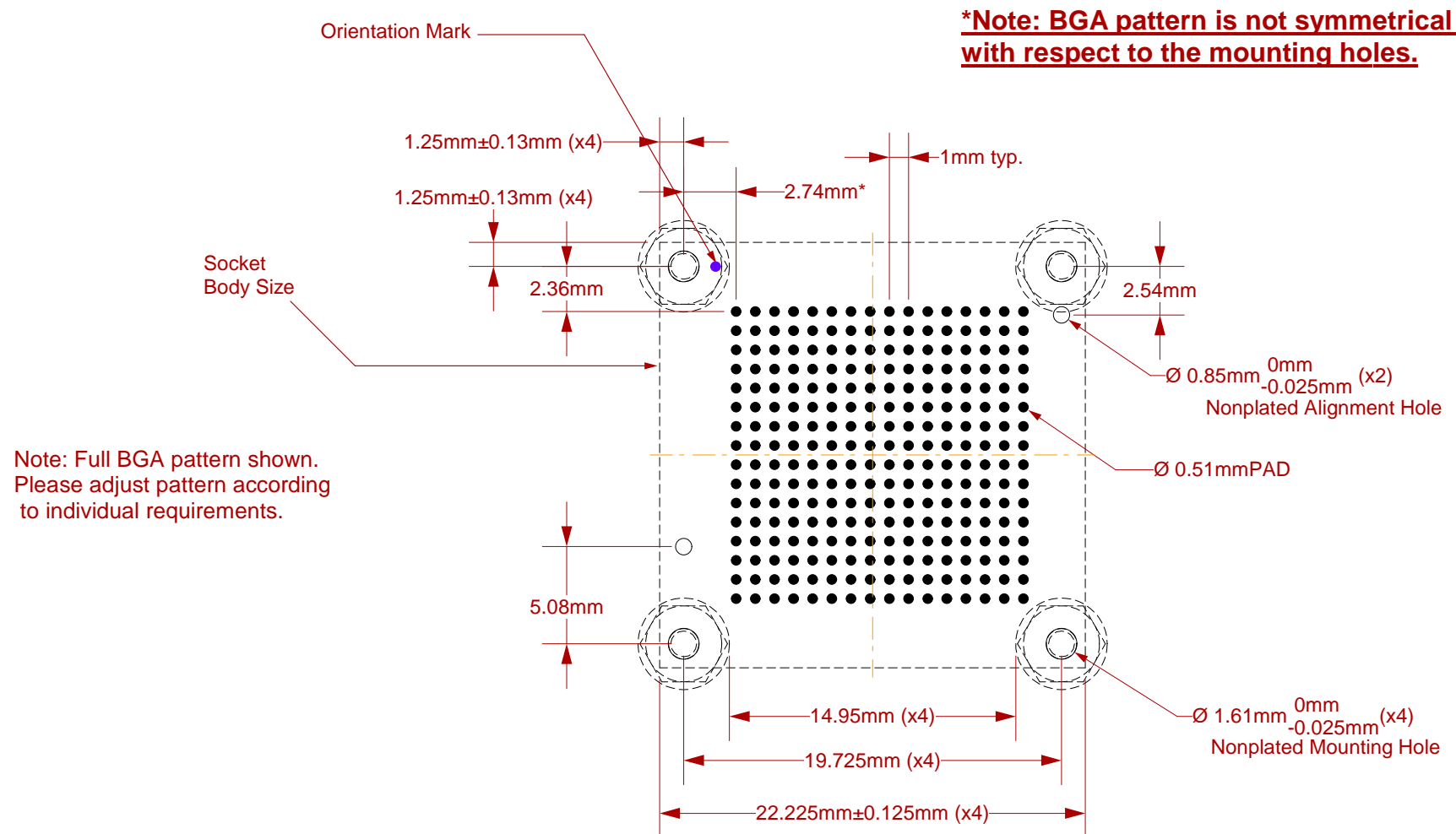
Drawing: H. Hansen

Date: 4/26/05

File: SG-BGA-6143 Dwg

Modified: 7/6/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.




Target PCB Recommendations

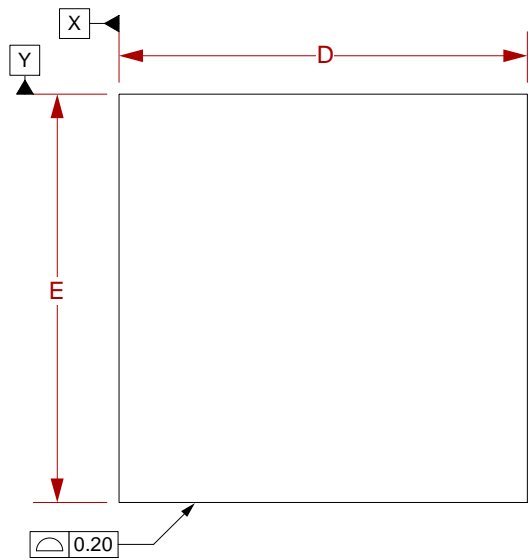
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

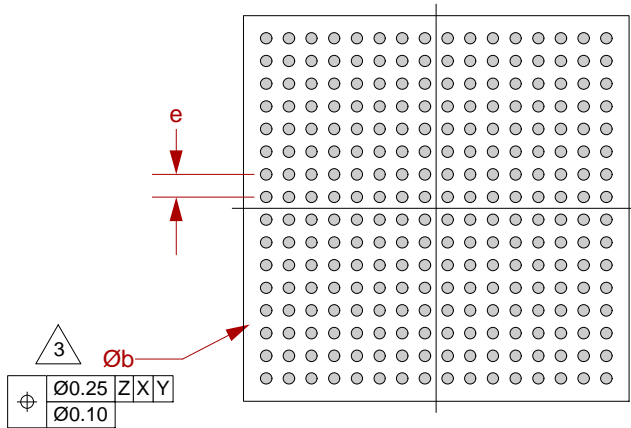
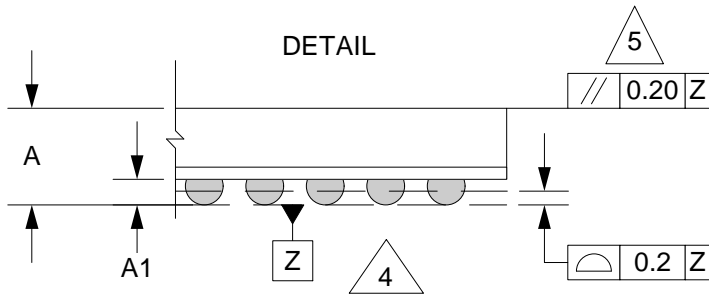
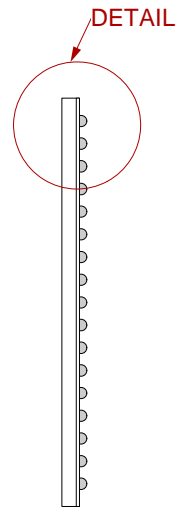
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-6143 Drawing	Status: Released	Scale: 3:1	Rev: B
 <p>© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen	Date: 4/26/05	
	File: SG-BGA-6143 Dwg	Modified: 7/6/09, AE	

TOP VIEW



SIDE VIEW



BOTTOM VIEW

- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.02
A1	0.3	0.5
b		0.6
D	17.00 BSC	
E	17.00 BSC	
e	1.0 BSC	

Array 16x16